# PATENT ASSIGNMENT

# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

# **CONVEYING PARTY DATA**

Name	Execution Date
Kuan-Yu Chen	08/14/2009
Hsien-Hsin Lin	08/14/2009
Chun-Feng Nieh	08/19/2009
Hsueh-Chang Sung	08/18/2009
Chien-Chang Su	08/14/2009
Tsz-Mei Kwok	08/14/2009

# **RECEIVING PARTY DATA**

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	
Street Address:	No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code:	300-77	

#### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12545705

# **CORRESPONDENCE DATA**

Fax Number: (214)200-0853

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

9727398643 Phone:

Email: linda.ingram@haynesboone.com Correspondent Name: HAYNES AND BOONE, LLP IP Section

Address Line 1: 2323 Victory Avenue

Address Line 2: Suite 700

Address Line 4: Dallas, TEXAS 75219

ATTORNEY DOCKET NUMBER: 24061.1313

**REEL: 023131 FRAME: 0976** 

**PATENT** 

500943391

NAME OF SUBMITTER:	Liem T. Do
Total Attachments: 4 source=1313Assignment#page1.tif source=1313Assignment#page2.tif source=1313Assignment#page3.tif source=1313Assignment#page4.tif	

PATENT REEL: 023131 FRAME: 0977

Customer No.: 42717

## ASSIGNMENT

WHEREAS, we,

(1)	Kuan-Yu Chen	of	1F, No. 5, Alley 3, Lane 91, Sec. 4, Bade Rd. Songshan District, Taipei City 105, Taiwan, R.O.C.
(2)	Hsien-Hsin Lin	of	11F-2, No. 21, 23 Lane, Guan-Dong Rd. Hsin-Chu City, Taiwan, R.O.C.
(3)	Chun-Feng Nieh	of	No. 103, Nankeng Rd. Baoshan Township Hsinchu County 308, Taiwan, R.O.C.
(4)	Hsueh-Chang Sung	of	3F., No. 208, Wencai St. Zhubei City, Hsinchu County 302, Taiwan, R.O.C.
(5)	Chien-Chang Su	of	No. 45, Rehe 1 <sup>st</sup> St., Sanmin District Kaohsiung City 807, Taiwan, R.O.C.
(6)	Tsz-Mei Kwok	of	Apt 9D, 128 Jin Shan Street Hsin-Chu, Taiwan, R.O.C.

have invented certain improvements in

## METHOD FOR IMPROVING SELECTIVITY OF EPI PROCESS

for which we have executed an application for Letters Patent of the United States of America on August 21, 2009, as U.S. Serial No. 12/545,705; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, whose duty

R-234298\_1.DOC - 1 -

Customer No.: 42717

it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor	Name:
TITACITOT	TAUTHO.

Kuan-Yu Chen

Residence Address:

1F, No. 5, Alley 3, Lane 91, Sec. 4, Bade Rd.

Songshan District, Taipei City 105, Taiwan, R.O.C.

Dated: V Kuan-Yn Chen

Inventor Signature

Inventor Name:

Hsien-Hsin Lin

Hoian Hain, Lin

Residence Address:

11F-2, No. 21, 23 Lane, Guan-Dong Rd.

Hsin-Chu City, Taiwan, R.O.C.

با . . . . . . ل

Inventor Signature

Customer No.: 42717

Inventor Name:

Chun-Feng Nieh

Residence Address:

No. 103, Nankeng Rd. Baoshan Township Hsinchu County 308, Taiwan, R.O.C.

Dated: \_\_\_\_\_ New Joseph / 8/19/2009

Inventor Name:

Hsueh-Chang Sung

Residence Address:

3F., No. 208, Wencai St.

Zhubei City, Hsinchu County 302, Taiwan, R.O.C.

Houch-Chang Sung

Customer No.: 42717

Inventor Name:

Chien-Chang Su

Residence Address:

No. 45, Rehe 1st St., Sanmin District Kaohsiung City 807, Taiwan, R.O.C.

Dated: 8/14/2009

Chien-Chang Sy Inventor Signature

Inventor Name:

Tsz-Mei Kwok

Residence Address:

No. 8, Li-Hsin Rd., 6, Science-Based Industrial Park

Hsin-Chu, Taiwan 300-77, R.O.C.

Dated: 8/14/2009

Ts7. Mei KwoK
Inventor Signature

-4-

R-1313 - Assignment 8-12-09 (dol)

**RECORDED: 08/21/2009** 

**PATENT REEL: 023131 FRAME: 0981**